



## Material Content Data Sheet



Sales Product Name	SAK-XC2364B-40F80L AA			Issued		29. August 2013		
MA#	MA001092652							
Package	PG-LQFP-100-8			Weight*		753.33 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	28.688	3.81	3.81	38081	38081
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.01		91	
	non noble metal	zinc	7440-66-6	0.275	0.04		365	
	non noble metal	iron	7439-89-6	5.501	0.73		7302	
	non noble metal	copper	7440-50-8	223.351	29.65	30.43	296485	304243
wire	noble metal	gold	7440-57-5	2.532	0.34	0.34	3361	3361
encapsulation	organic material	carbon black	1333-86-4	2.362	0.31		3136	
	plastics	epoxy resin	-	63.786	8.47		84672	
	inorganic material	silicondioxide	60676-86-0	406.340	53.93	62.71	539392	627200
leadfinish	non noble metal	tin	7440-31-5	9.288	1.23	1.23	12330	12330
plating	noble metal	silver	7440-22-4	2.495	0.33	0.33	3312	3312
glue	plastics	epoxy resin	-	2.161	0.29		2868	
	noble metal	silver	7440-22-4	6.482	0.86	1.15	8605	11473
*deviation	< 10%	Sum in total:			100,00			1000000

### Important Remarks:

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